



HYCLEANSE® 300

Entec Polymers - High Density Polyethylene

Tuesday, November 5, 2019

General Information

Product Description

HYCLEANSE 300 Purge contains several proprietary additives that are essential in the cleansing process of high temperatures and lower melting polyolefins. HyCleanse 300 Purge was created to be the least cost prohibitive cleansing compound on the market today. HyCleanse 300 Purge can be used directly without any mixing necessary to clean most plastics equipment during color and resin changes. The unique additives and resin system in HyCleanse 300 Purge, makes it possible to purge color resins like Polyolefins, A.B.S., Styrenics, HDPE, as well as high temperature materials such as PEEK and Polysulfone in less time, in most resin applications.

Features and Benefits:

HyCleanse-300 Purge is easy to use and no process changes are needed. Use at the normal resin processing temperature and RPM speed. No mixing is required. Also HyCleanse-300 Purge is not just a Mechanical purge.

Applications: Injection Molding - Pipe/Profile - Compounding

Types of Resins: PE, PP, PS, PA, POM, ABS, PEEK, PC/ABS

General

Material Status	• Commercial: Active
Availability	• North America
Additive	• Proprietary
Uses	• Purging Compound
Agency Ratings	• FDA Unspecified Rating

ASTM & ISO Properties ¹

Physical	Nominal Value	Unit
Density	0.955	g/cm ³
Apparent (Bulk) Density	0.72 to 0.88	g/cm ³
Melt Mass-Flow Rate (190°C/2.16 kg)	0.30 to 0.50	g/10 min

Additional Information	Nominal Value	Unit
Temperature Range	350 to 600	°F

Notes

¹ Typical properties: these are not to be construed as specifications.